



Integrated Device Technology, Inc.

VERY LOW POWER **3.3V CMOS FAST SRAM** **256K (32K x 8-BIT)**

PRELIMINARY
INFORMATION
IDT713256SL

FEATURES

- Ideal for 16/32-bit notebook/sub-notebook cache at 20, 25, and 33MHz, and for other battery-operated equipment
- Very low standby current (maximums):
 - 3.0mA standby
 - 500uA full standby
- Fast access times:
 - 20/25/30ns
- Battery-backup operation: 2V data retention
 - 300uA data retention current (max.)
- Small package for space-efficient layouts:
 - 28-pin 300 mil SOJ
- Ideal configuration for large cache sizes, with minimum space and minimum power:
 - 32K x 8
- Produced with advanced high-performance CMOS technology
- Input and output are TTL-compatible
- Single 3.3V(±0.3V) power supply

DESCRIPTION

The IDT713256SL is a 262,144-bit high-speed static RAM organized as 32K x 8. It is fabricated using IDT's high-performance, high-reliability CMOS technology.

The IDT713256SL has outstanding low power characteristics, as well as fast speeds.

Address access times of 20, 25, and 30ns are ideal for 16 and 32-bit notebook and laptop cache designs running at 20, 25, and 33MHz, and operating from 3.3 volts. For instance, two of these SRAMs interface directly to many 386 notebook cache controllers to form a 64kB cache. Portable communications and test equipment benefit from these fast speeds and low power too.

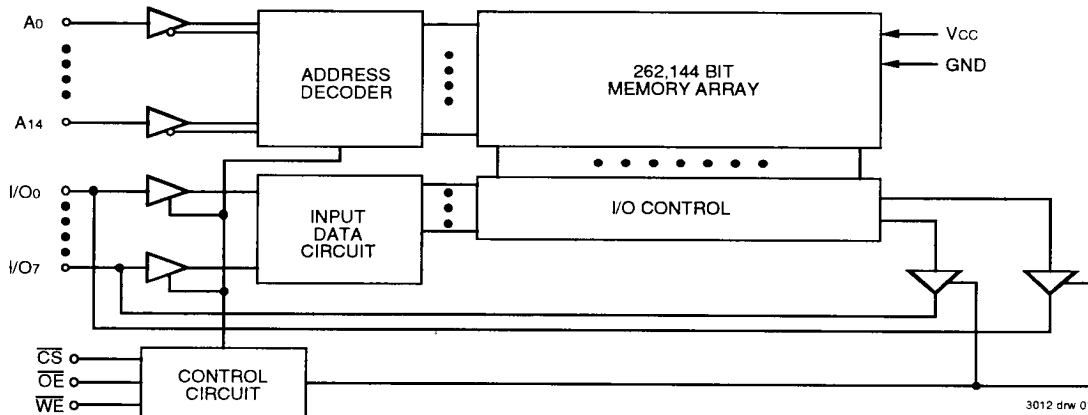
When the power management logic puts the IDT713256SL in standby mode, its very low power characteristics contribute to extended battery life.

When CS goes HIGH, the SRAM will automatically go to a low power standby mode and will remain in standby as long as CS remains HIGH. Furthermore, under full standby mode (CS at CMOS level, t=0), power consumption is guaranteed to always be less than 1.65mW and typically will be much smaller.

This SRAM also offers battery-backup data retention at as little as 2 volts. Under this condition, power consumption is guaranteed not to exceed 1.0mW and typically will be much smaller.

The package chosen for this device, 28-pin 300mil SOJ, helps the designer attain the stringent space goals typical of notebooks, sub-notebooks, and battery-operated portable equipment.

FUNCTIONAL BLOCK DIAGRAM



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COMMERCIAL TEMPERATURE RANGES

SEPTEMBER 1992

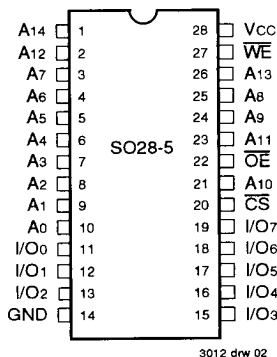
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DSC-1100-

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PIN CONFIGURATIONS

SOJ
TOP VIEWABSOLUTE MAXIMUM RATINGS⁽¹⁾

Symbol	Rating	Com'l.	Unit
V _{TERM} ⁽²⁾	Terminal Voltage with Respect to GND	-0.5 to +4.6	V
V _{TERM} ⁽³⁾	Terminal Voltage with Respect to GND	-0.5 to V _{CC} +0.5	V
T _A	Operating Temperature	0 to +70	°C
T _{BIAS}	Temperature Under Bias	-55 to +125	°C
T _{STG}	Storage Temperature	-55 to +125	°C
P _T	Power Dissipation	1.0	W
I _{OUT}	DC Output Current	50	mA

NOTES:

3012 tbl 03

- Stresses greater than those listed under ABSOLUTE MAXIMUM RATINGS may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.
- V_{CC} terminals only
- Input, Output, and I/O terminals; 4.6V maximum

PIN DESCRIPTIONS

Name	Description
A ₀ -A ₁₄	Addresses
I/O ₀ -I/O ₇	Data Input/Output
$\overline{CS}$	Chip Select
WE	Write Enable
$\overline{OE}$	Output Enable
GND	Ground
V _{CC}	Power

3012 tbl 01

CAPACITANCE (T_A = +25°C, f = 1.0MHz,
SOJ package)

Symbol	Parameter ⁽¹⁾	Conditions	Max.	Unit
C _{IN}	Input Capacitance	V _{IN} = 3dV	5	pF
C _{OUT}	Output Capacitance	V _{OUT} = 3dV	7	pF

NOTE:

3012 tbl 04

- This parameter is determined by device characterization, but is not production tested.

RECOMMENDED OPERATING
TEMPERATURE AND SUPPLY VOLTAGE

Grade	Temperature	GND	V _{CC}
Commercial	0°C to +70°C	0V	3.3V ± 0.3V

3012 tbl 05

RECOMMENDED DC OPERATING
CONDITIONS

Symbol	Parameter	Min.	Typ.	Max.	Unit
V _{CC}	Supply Voltage	3.0	3.3	3.6	V
GND	Supply Voltage	0	0	0	V
V _{IH}	Input High Voltage	2.0	—	V _{CC} +0.3	V
V _{IL}	Input Low Voltage	-0.5 ⁽¹⁾	—	0.8	V

NOTE:

3012 tbl 06

- V_{IL} (min.) = -1.0V for pulse width less than 5ns, once per cycle.

TRUTH TABLE⁽¹⁾

WE	$\overline{CS}$	$\overline{OE}$	I/O	Function
X	H	X	High-Z	Standby (ISB)
X	V _{HC}	X	High-Z	Standby (ISB1)
H	L	H	High-Z	Output Disable
H	L	L	DOUT	Read
L	L	X	DIN	Write

3012 tbl 02

NOTE:

- H = V_{IH}, L = V_{IL}, X = Don't Care

DC ELECTRICAL CHARACTERISTICS^(1, 2)

(VCC = 3.3V ± 0.3V, VLC = 0.2V, VHC = VCC - 0.2V)

Symbol	Parameter	Power	713256SL20 Com'l.	713256SL25 Com'l.	713256SL30 Com'l.	Unit
ICC	Dynamic Operating Current $\overline{CS} \leq V_{IL}$, Outputs Open, $V_{CC} = \text{Max.}$, $f = f_{\text{MAX}}^{(2)}$	SL	95	90	85	mA
ISB	Standby Power Supply Current (TTL Level) $\overline{CS} = V_{IH}$, $V_{CC} = \text{Max.}$, Outputs Open, $f = f_{\text{MAX}}^{(2)}$	SL	3	3	3	mA
ISB1	Full Standby Power Supply Current (CMOS Level) $\overline{CS} \geq V_{HC}$, $V_{CC} = \text{Max.}$, $f = 0$	SL	0.5	0.5	0.5	mA

NOTES:

1. All values are maximum guaranteed values.

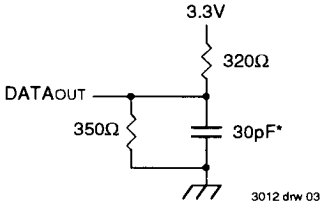
2. $f_{\text{MAX}} = 1/t_{RC}$, only address inputs cycling at f_{MAX} ; $f = 0$ means that no inputs are cycling.

3012 tbi 07

AC TEST CONDITIONS

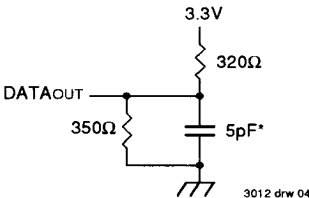
Input Pulse Levels	GND to 3.0V
Input Rise/Fall Times	3ns
Input Timing Reference Levels	1.5V
Output Reference Levels	1.5V
AC Test Load	See Figures 1 and 2

3012 tbi 08



3012 drw 03

Figure 1. AC Test Load



3012 drw 04

Figure 2. AC Test Load
(for tCLZ, tOLZ, tCHZ, tOHZ, tOW, tWHZ)

*Includes scope and jig capacitances

DC ELECTRICAL CHARACTERISTICS

VCC = 3.3V ± 0.3V

Symbol	Parameter	Test Condition	IDT713256SL			Unit
			Min.	Typ.	Max.	
ILI	Input Leakage Current	$V_{CC} = \text{Max.}$, $V_{IN} = \text{GND to } V_{CC}$	—	—	2	μA
ILO	Output Leakage Current	$V_{CC} = \text{Max.}$, $\overline{CS} = V_{IH}$, $V_{OUT} = \text{GND to } V_{CC}$	—	—	2	μA
VOL	Output Low Voltage	$I_{OL} = 8\text{mA}$, $V_{CC} = \text{Min.}$	—	—	0.4	V
VOH	Output High Voltage	$I_{OH} = -4\text{mA}$, $V_{CC} = \text{Min.}$	2.4	—	—	V

3012 tbi 09

DATA RETENTION CHARACTERISTICS OVER ALL TEMPERATURE RANGES

V_{LC} = 0.2V, V_{HC} = V_{CC} – 0.2V

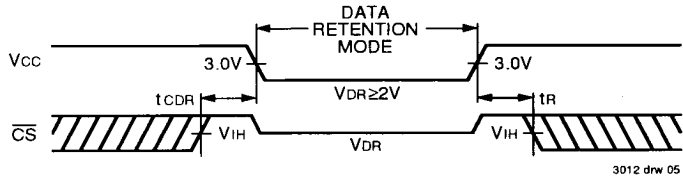
Symbol	Parameter	Test Condition	Min.	Typ. ⁽¹⁾ V _{CC} @ 2.0v	Max. V _{CC} @ 2.0V	Unit
				2.0v	2.0V	
V _{DR}	VCC for Data Retention	—	2.0	—	—	V
I _{CCDR}	Data Retention Current	$\overline{CS} \geq V_{HC}$	—	—	300	μA
t _{CDR}	Chip Deselect to Data Retention Time		0	—	—	ns
t _R ⁽³⁾	Operation Recovery Time		t _{RC} ⁽²⁾	—	—	ns

NOTES:

- 1. T_A = +25°C.
- 2. t_{RC} = Read Cycle Time.
- 3. This parameter is guaranteed, but is not production tested.

3012 tbl 10

LOW V_{CC} DATA RETENTION WAVEFORM



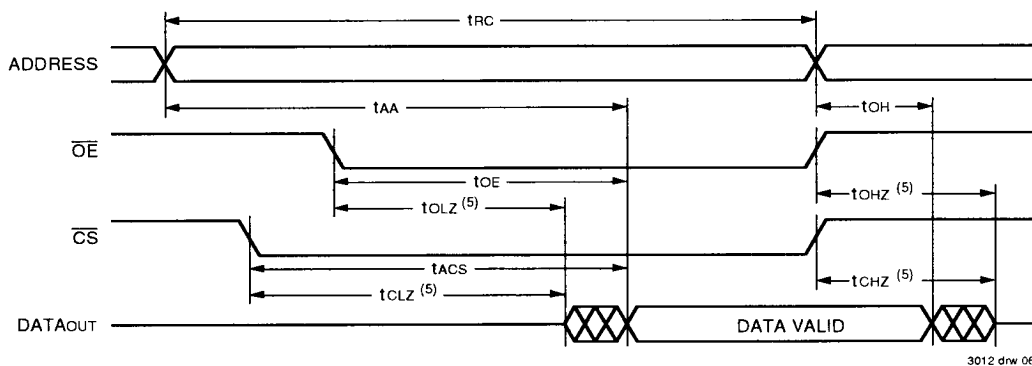
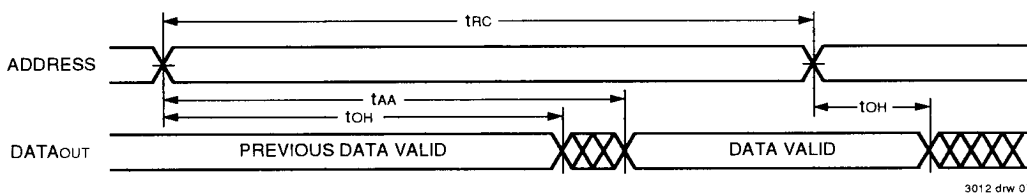
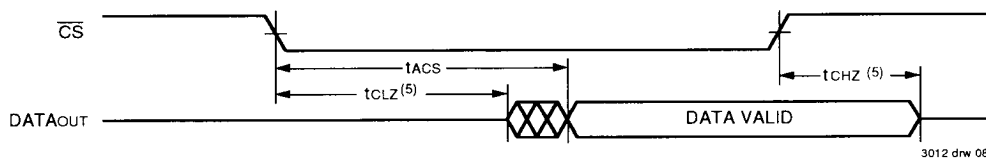
AC ELECTRICAL CHARACTERISTICS ($V_{CC} = 3.3V \pm 0.3V$, ALL TEMPERATURE RANGES)

		713256SL20		713256SL25		713256SL30		
Symbol	Parameter	Min.	Max.	Min.	Max.	Min.	Max.	Unit
Read Cycle								
tRC	Read Cycle Time	20	—	25	—	30	—	ns
tAA	Address Access Time	—	20	—	25	—	30	ns
tACS	Chip Select Access Time	—	20	—	25	—	30	ns
tCLZ	Chip Select to Output in Low-Z ⁽¹⁾	5	—	5	—	5	—	ns
tOE	Output Enable to Output Valid	—	8	—	10	—	13	ns
tOLZ	Output Enable to Output in Low-Z ⁽¹⁾	3	—	3	—	3	—	ns
tCHZ	Chip Select to Output in High-Z ⁽¹⁾	0	10	0	11	0	13	ns
tOHZ	Output Disable to Output in High-Z ⁽¹⁾	2	8	2	10	2	13	ns
tOH	Output Hold from Address Change	5	—	5	—	5	—	ns
Write Cycle								
tWC	Write Cycle Time	20	—	25	—	30	—	ns
tCW	Chip Select to End-of-Write	15	—	20	—	25	—	ns
tAW	Address Valid to End-of-Write	15	—	20	—	25	—	ns
tAS	Address Set-up Time	0	—	0	—	0	—	ns
tWP	Write Pulse Width	15	—	15	—	25	—	ns
tWR	Write Recovery Time	0	—	0	—	0	—	ns
tWHZ	Write Enable to Output in High-Z ⁽¹⁾	1	10	1	11	1	13	ns
tDW	Data to Write Time Overlap	8	—	10	—	13	—	ns
tDH1	Data Hold from Write Time (WE)	0	—	0	—	0	—	ns
tDH2	Data Hold from Write Time (CS)	0	—	0	—	0	—	ns
tOW	Output Active from End-of-Write ⁽¹⁾	5	—	5	—	5	—	ns

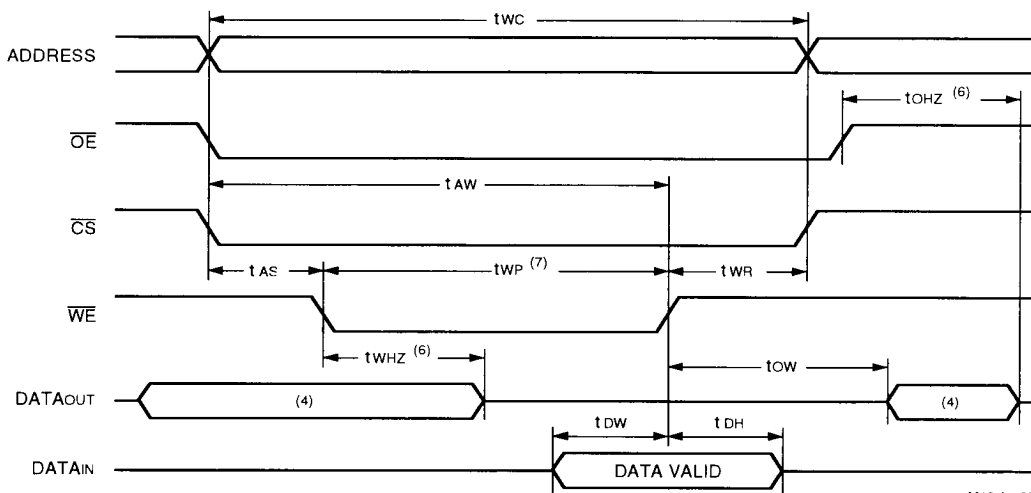
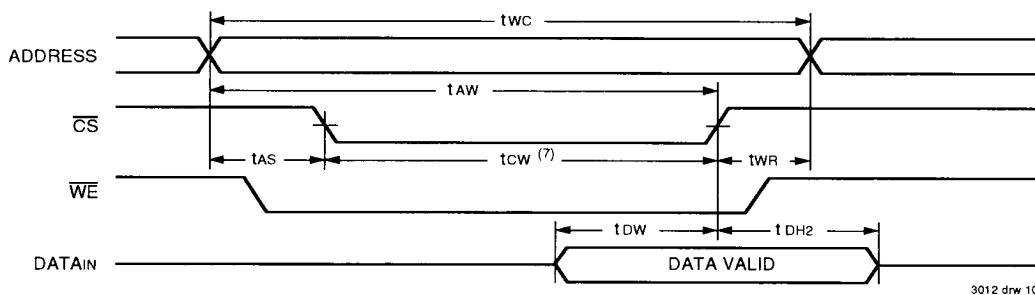
NOTE:

3012 tbl 11

1. This parameter guaranteed with the AC test load (Figure 2) by device characterization, but is not production tested.

TIMING WAVEFORM OF READ CYCLE NO. 1⁽¹⁾**TIMING WAVEFORM OF READ CYCLE NO. 2^(1, 2, 4)****TIMING WAVEFORM OF READ CYCLE NO. 3^(1, 3, 4)****NOTES:**

1. $\overline{WE}$ is HIGH for read cycle.
2. Device is continuously selected, $\overline{CS} = V_{IL}$.
3. Address valid prior to or coincident with $\overline{CS}$ transition low.
4. $\overline{OE} = V_{IL}$.
5. Transition is measured $\pm 200\text{mV}$ from steady state.

TIMING WAVEFORM OF WRITE CYCLE NO. 1 ($\overline{WE}$ CONTROLLED TIMING)(1, 2, 3, 5, 7)**TIMING WAVEFORM OF WRITE CYCLE NO. 2 ($\overline{CS}$ CONTROLLED TIMING)**(1, 2, 3, 5)**NOTES:**

1. $\overline{WE}$ or $\overline{CS}$ must be HIGH during all address transitions.
2. A write occurs during the overlap of a LOW $\overline{CS}$ and a LOW $\overline{WE}$.
3. t_{WR} is measured from the earlier of $\overline{CS}$ or $\overline{WE}$ going HIGH to the end of the write cycle.
4. During this period, I/O pins are in the output state so that the input signals must not be applied.
5. If the $\overline{CS}$ LOW transition occurs simultaneously with or after the $\overline{WE}$ LOW transition, the outputs remain in a high-impedance state.
6. Transition is measured $\pm 200\text{mV}$ from steady state.
7. If $\overline{OE}$ is LOW during a $\overline{WE}$ controlled write cycle, the write pulse width must be the larger of t_{WP} or $(t_{WHZ} + t_{OW})$ to allow the I/O drivers to turn off and data to be placed on the bus for the required t_{OW} . If $\overline{OE}$ is HIGH during a $\overline{WE}$ controlled write cycle, this requirement does not apply and the write pulse can be as short as the specified t_{WP} .

ORDERING INFORMATION

